



Material Content Data Sheet



Sales Product Name		SAK-XC167CI-32F40F BB-A		Issued		29. August 2013			
MA#		MA000945714							
Package		PG-TQFP-144-7		Weight*		1402.20 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	33.010	2.35	2.35	23541	23541	
leadframe	non noble metal	magnesium	7439-95-4	0.529	0.04		377		
	inorganic material	silicon	7440-21-3	2.293	0.16		1635		
	non noble metal	nickel	7440-02-0	10.581	0.75		7546		
	non noble metal	copper	7440-50-8	339.310	24.20	25.15	241985	251543	
wire	noble metal	gold	7440-57-5	3.590	0.26	0.26	2560	2560	
encapsulation	organic material	carbon black	1333-86-4	4.981	0.36		3552		
	plastics	epoxy resin	-	134.483	9.59		95909		
	inorganic material	silicondioxide	60676-86-0	856.707	61.10	71.05	610975	710436	
leadfinish	non noble metal	tin	7440-31-5	8.638	0.62	0.62	6160	6160	
plating	noble metal	silver	7440-22-4	4.833	0.34	0.34	3447	3447	
glue	plastics	epoxy resin	-	0.649	0.05		463		
	noble metal	silver	7440-22-4	2.595	0.18	0.23	1850	2313	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

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